

L1: TOP CONDUCTOR - COPPER 2.7 MIL

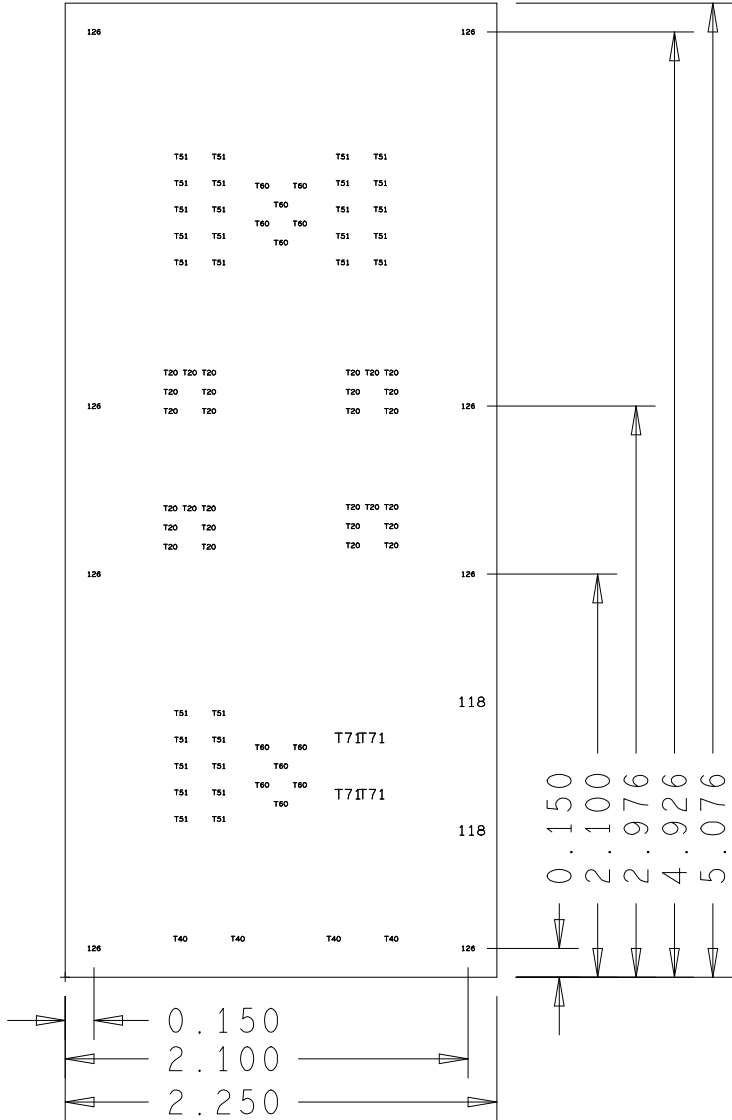
CORE - FR-4 59 MIL

L2: BOTTOM CONDUCTOR - COPPER 2.7 MIL

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
T20	20.0	PLATED	28
T40	40.0	PLATED	4
T51	51.0	PLATED	30
T60	60.0	PLATED	12
T71	71.0	PLATED	4
118	118.0	PLATED	2
126	126.0	NON-PLATED	8

DESIGN CROSS SECTION CHART
TOTAL THICKNESS 64.4 MIL



CLASS II FABRICATION NOTES: (UNLESS OTHERWISE SPECIFIED)

- BOARDS SHALL BE 100% NET LIST TESTED FOR OPENS AND SHORTS PER PROVIDED IPC-D-356 NETLIST.
- THIS BOARD SHALL BE MANUFACTURED IN ACCORDANCE WITH IPC-6012A CLASS II SPECIFICATIONS AND MEET IPC-600 CLASS II ACCEPTABILITY STANDARDS.
- MATERIAL:
 - FR4 PER IPC 4101B/24, /26, OR /28.
 - SIGNAL LAYERS TO BE 2 OZ. COPPER.
 - ~~PLANE LAYERS TO BE 1 OZ. COPPER.~~
 - OVERALL THICKNESS TO BE 0.062" +/- 10%
- LEGEND:
 - WHITE NON-CONDUCTIVE EPOXY INK BOTH SIDES.
- SOLDERMASK:
 - APPLY LIQUID PHOTO-IMAGABLE (LPI) SOLDER MASK OVER BARE COPPER PER IPC-SM-840 CLASS H, COLOR RED, BOTH SIDES.
- PLATING FINISH:
 - HOT AIR SOLDER LEVELING (HASL) SN63A SnPb SOLDER.
 - ~~IMMERSION SILVER IAG.~~
- PROCESS ALLOWANCES:
 - MAXIMUM BOW AND TWIST ACROSS DIAGONAL CORNERS OF THE BOARD SHALL NOT EXCEED 0.75%.
 - HOLE DIMENSIONS APPLY AFTER PLATING.
 - ALL HOLES SHALL BE LOCATED WITHIN 0.003" DIAMETER OF TRUE POSITION.
 - LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003".
 - CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/- 0.002".
 - REMOVE ALL BURRS AND BREAK SHARP EDGES 0/015" MAX.
 - CUT OUTSIDE OF 0.001" BOARD OUTLINE.

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	LRAUV - POWER INTERFACE BOARD			
DIMENSIONS ARE IN INCHES TOLERANCES ON: 2 PL DECIMALS +/- 0.02" 3 PL DECIMALS +/- 0.005" ANGLES +/- 1 Degree FRACTIONS +			MONTEREY BAY AQUARIUM RESEARCH INSTITUTE 7700 SANDHOLDT ROAD MOSS LANDING, CA			
			SIZE B	REVISION A	DWG NO 10021057-PIB1	
	DESIGNED BY: DENIS KLIMOV		SCALE 1 - 1		SHEET 1 - 1	
	LAYOUT BY: JOSE ROSAL					